



10N30-HC

Preliminary

Power MOSFET

10A, 300V N-CHANNEL POWER MOSFET

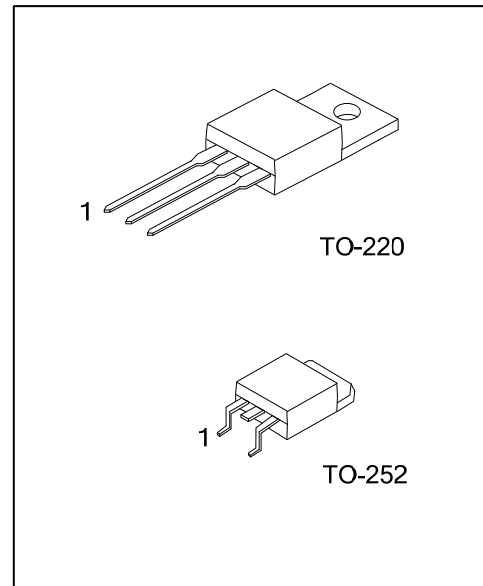
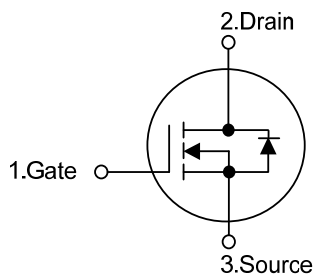
DESCRIPTION

The **UTC 10N30-HC** is a high voltage and high current power MOSFET, designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient AC to DC converters and bridge circuits.

FEATURES

- * $R_{DS(ON)} \leq 0.7 \Omega$ @ $V_{GS}=10V$, $I_D=5.0A$
- * Fast switching
- * Improved dv/dt capability

SYMBOL



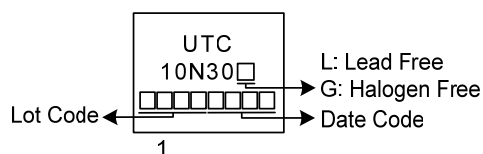
ORDERING INFORMATION

Ordering Number		Package	Pin Assignment			Packing
Lead Free	Halogen Free		1	2	3	
10N30L-TA3-T	10N30G-TF3-T	TO-220	G	D	S	Tube
10N30L-TN3-R	10N30G-TN3-R	TO-252	G	D	S	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source

<p>10N30G-TF3-T</p> <p>(1) Packing Type</p> <p>(2) Package Type</p> <p>(3) Green Package</p>		<p>(1) T: Tube, R: Tape Reel</p> <p>(2) TA3: TO-220, TN3: TO-252</p> <p>(3) G: Halogen Free and Lead Free, L: Lead Free</p>
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MARKING



■ ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DS}	300	V
Gate-Source Voltage		V_{GS}	± 30	V
Drain Current	Continuous	I_D	10	A
	Pulsed (Note 2)	I_{DM}	20	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	27	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	1.9	V/ns
Power Dissipation	TO-220	P_D	60	W
	TO-252		45	W
Junction Temperature		T_J	+150	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ +150	$^\circ\text{C}$

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

2. Repetitive Rating: Pulse width limited by maximum junction temperature.

3. $L = 1.0\text{mH}$, $I_{AS} = 7.3\text{A}$, $V_{DD} = 50\text{V}$, $R_G = 25\ \Omega$ Starting $T_J = 25^\circ\text{C}$

4. $I_{SD} \leq 10\text{A}$, $di/dt \leq 200\text{A}/\mu\text{s}$, $V_{DD} \leq BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	TO-220	θ_{JA}	62.5	$^\circ\text{C}/\text{W}$
	TO-252		110	
Junction to Case	TO-220	θ_{JC}	2.08	$^\circ\text{C}/\text{W}$
	TO-252		2.7 (Note)	

Note: Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

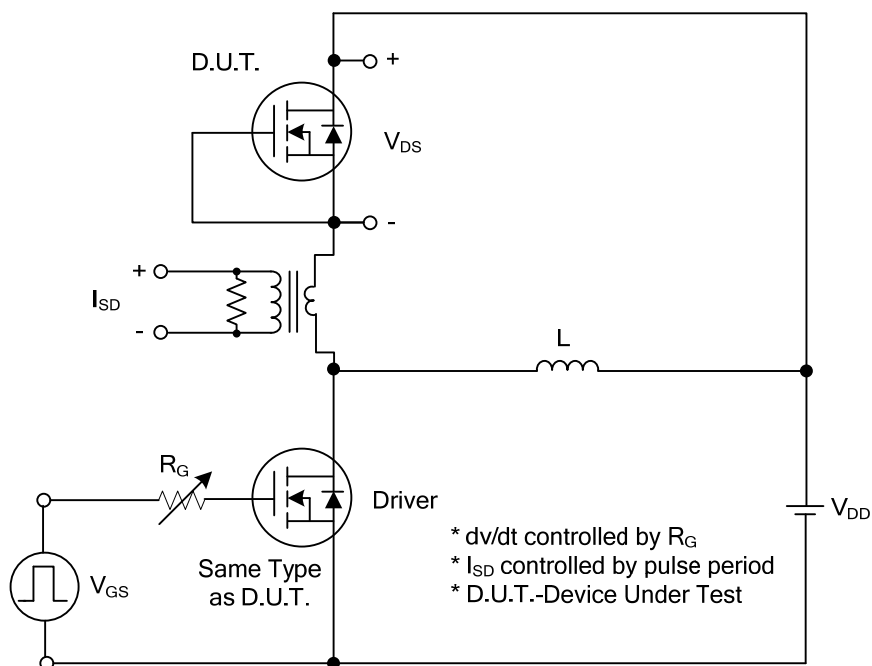
■ ELECTRICAL CHARACTERISTICS ($T_J = 25^\circ\text{C}$, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	V _{GS} =0V, I _D = 250μA	300			V
Drain-Source Leakage Current		I _{DSS}	V _{DS} =300V, V _{GS} =0V			10	μA
Gate-Source Leakage Current	Forward	I _{GSS}	V _{GS} =30V, V _{DS} =0V			100	nA
	Reverse		V _{GS} =-30V, V _{DS} =0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		V _{GS(TH)}	V _{DS} =V _{GS} , I _D =250μA	2.0		4.0	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	V _{GS} =10V, I _D =5.0A			0.7	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C _{ISS}	V _{GS} =0V, V _{DS} =25V, f=1.0 MHz		436.9		pF
Output Capacitance		C _{OSS}			66.8		pF
Reverse Transfer Capacitance		C _{RSS}			4.6		pF
SWITCHING CHARACTERISTICS							
Total Gate Charge (Note 1)		Q _G	V _{DS} =240V, V _{GS} =10V, I _D =10A I _G =1mA (Note 1, 2)		13.3		nC
Gateource Charge		Q _{GS}			4.8		nC
Gate-Drain Charge		Q _{GD}			1.6		nC
Turn-on Delay Time (Note 1)		t _{D(ON)}	V _{DD} =100V, V _{GS} =10V,, I _D =10A, R _G =25Ω (Note 1, 2)		5.8		ns
Rise Time		t _R			16.4		ns
Turn-off Delay Time		t _{D(OFF)}			24.6		ns
Fall-Time		t _F			20.6		ns
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS							
Maximum Continuous Drain-Source Diode Forward Current		I _S				10	A
Maximum Pulsed Drain-Source Diode Forward Current		I _{SM}				20	A
Drain-Source Diode Forward Voltage (Note 1)		V _{SD}	V _{GS} =0V, I _S =10A			1.4	V
Reverse Recovery Time (Note 1)		t _{rr}	V _{GS} =0V, I _S =10A,		158		ns
Reverse Recovery Charge		Q _{rr}	dl _F /dt=100A/μs (Note1)		1.89		μC

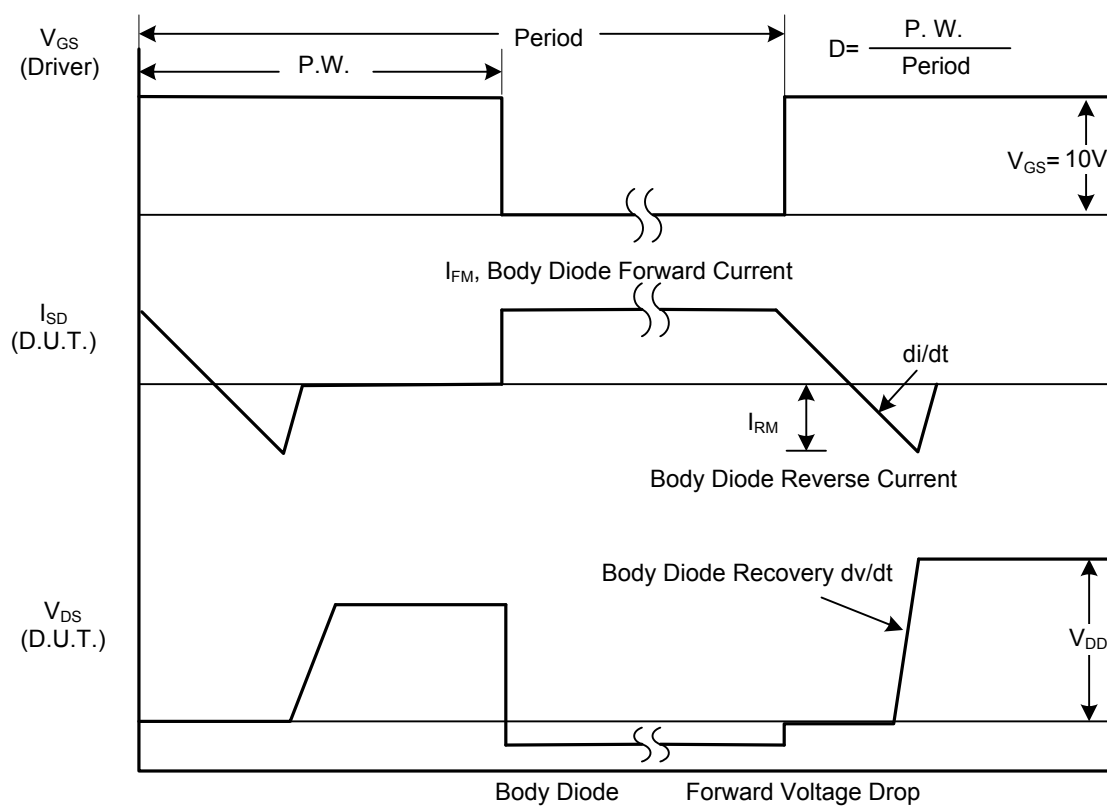
Notes: 1. Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$.

2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

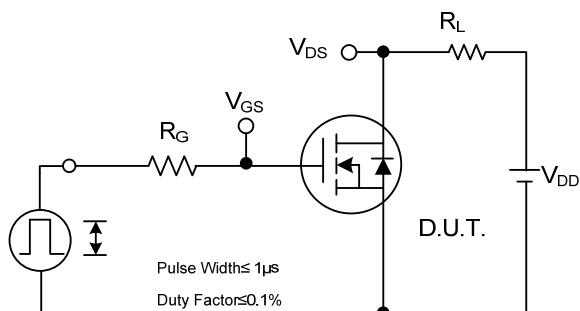


Peak Diode Recovery dv/dt Test Circuit

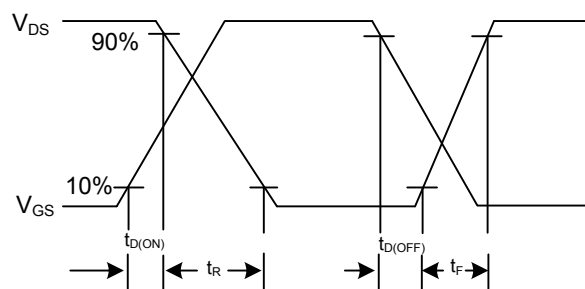


Peak Diode Recovery dv/dt Waveforms

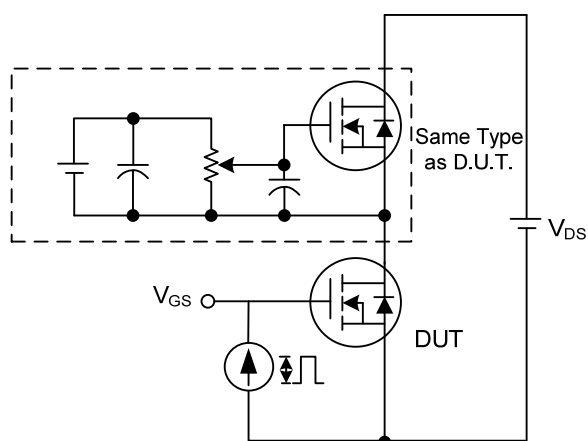
■ TEST CIRCUITS AND WAVEFORMS



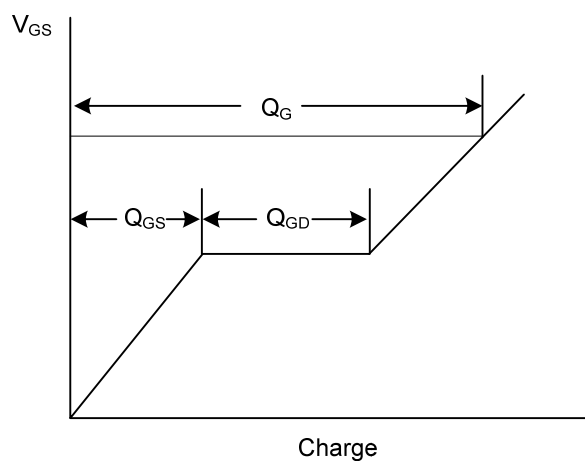
Switching Test Circuit



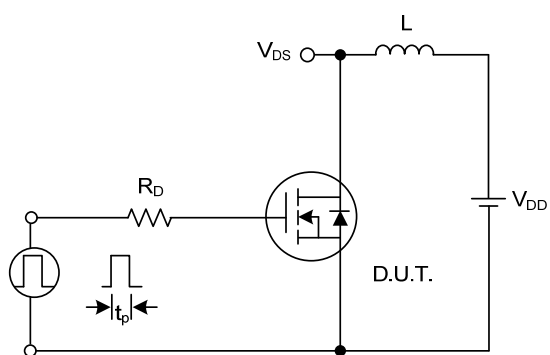
Switching Waveforms



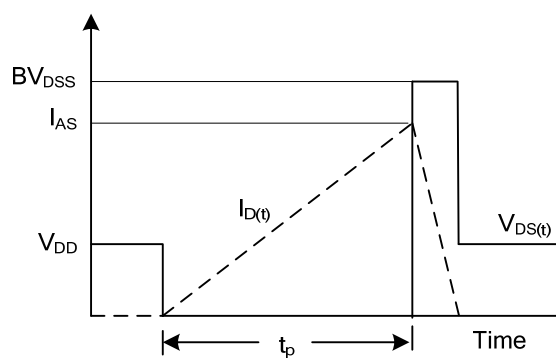
Gate Charge Test Circuit



Gate Charge Waveform



Unclamped Inductive Switching Test Circuit



Unclamped Inductive Switching Waveforms

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